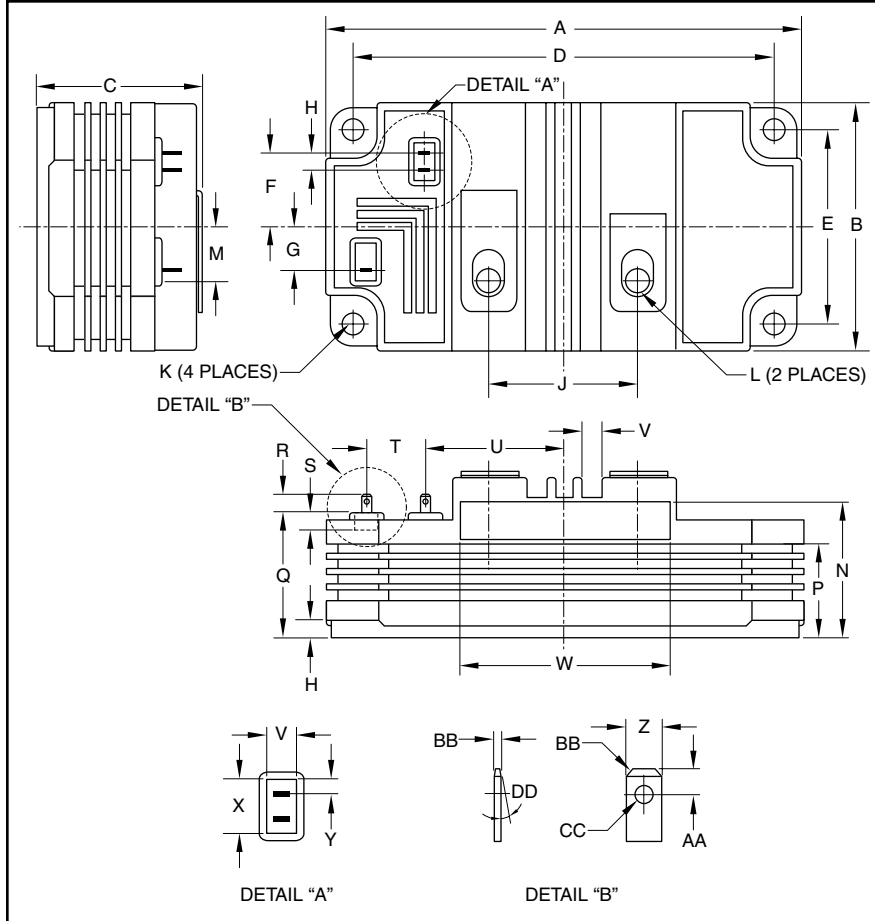


### Single IGBTMOD™ HVIGBT Module 200 Amperes/6500 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	5.51	140.0
B	2.87	73.0
C	1.89+0.04/-0.0	48.0+1.0/-0.0
D	4.88	124.0
E	2.24	57.0
F	0.85	21.6
G	0.51	12.9
H	0.20	5.0
J	1.73	44.0
K	M6 Metric	M6
L	M8 Metric	M8
M	0.64	16.2
N	1.59	40.4
P	1.10	28.0

Dimensions	Inches	Millimeters
Q	1.44	36.5
R	0.22	5.5
S	0.16	4.0
T	0.68	17.4
U	1.61	41.0
V	0.24	6.0
W	2.44	62.0
X	0.47	12.0
Y	0.14	3.5
Z	0.11	2.8
AA	0.06	1.6
BB	0.02	0.5
CC	0.05 Dia.	1.2 Dia.
DD	10°	10°



#### Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of one IGBT Transistor in a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low Drive Power
- Low  $V_{CE(sat)}$
- Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- Traction
- Medium Voltage Drives
- High Voltage Power Supplies

#### Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM200HG-130H is a 6500V ( $V_{CES}$ ), 200 Ampere Single IGBTMOD™ Power Module.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	200	130



Powerex, Inc., 200 E. Hillis Street, Youngwood, Pennsylvania 15697-1800 (724) 925-7272

**CM200HG-130H**  
**Single IGBTMOD™ HVIGBT Module**  
 200 Amperes/6500 Volts

**Absolute Maximum Ratings,  $T_j = 25\text{ °C}$  unless otherwise specified**

Ratings	Symbol	CM200HG-130H	Units
Junction Temperature	$T_j$	-40 to 150	°C
Storage Temperature	$T_{stg}$	-40 to 125	°C
Operating Temperature	$T_{opr}$	-40 to 125	°C
Collector-Emitter Voltage ( $V_{GE} = 0V, T_j = -40\text{ °C}$ )	$V_{CES}$	5800	Volts
Collector-Emitter Voltage ( $V_{GE} = 0V, T_j = +25\text{ °C}$ )	$V_{CES}$	6300	Volts
Collector-Emitter Voltage ( $V_{GE} = 0V, T_j = +125\text{ °C}$ )	$V_{CES}$	6500	Volts
Gate-Emitter Voltage ( $V_{CE} = 0V$ )	$V_{GES}$	±20	Volts
Collector Current (DC, $T_c = 80\text{ °C}$ )	$I_C$	200	Amperes
Peak Collector Current (Pulse)	$I_{CM}$	400*	Amperes
Emitter Current** ( $T_c = 25\text{ °C}$ )	$I_E$	200	Amperes
Emitter Surge Current** (Pulse)	$I_{EM}$	400*	Amperes
Maximum Collector Dissipation ( $T_c = 25\text{ °C}$ , IGBT Part, $T_{j(max)} \leq 125\text{ °C}$ )	$P_C$	2900	Watts
Partial Discharge ( $V_1 = 6900\text{ V}_{rms}, V_2 = 5100\text{ V}_{rms}, 60\text{ Hz}$ (Acc. to IEC 1287))	$Q_{pd}$	10	pC
Max. Mounting Torque M8 Main Terminal Screws	–	133	in-lb
Max. Mounting Torque M6 Mounting Screws	–	53	in-lb
Module Weight (Typical)	–	0.52	kg
Isolation Voltage (Charged Part to Baseplate, AC 60Hz 1 min.)	$V_{iso}$	10200	Volts
Maximum Turn-Off Switching Current ( $V_{CC} \leq 4500V, V_{GE} = \pm 15V, R_{G(off)} \geq 72\Omega, T_j = 125\text{ °C}$ )	–	400	Amperes
Short Circuit Capability, Maximum Pulse Width ( $V_{CC} \leq 4500V, V_{GE} = \pm 15V, R_{G(off)} \geq 72\Omega, T_j = 125\text{ °C}$ )	–	10	µs
Maximum Reverse Recovery Instantaneous Power ( $V_{CC} \leq 4500V, di_e/dt \leq 1000A/\mu s, T_j = 125\text{ °C}$ )	–	1200	kW

\* Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{oprmax}$  rating (125°C).

\*\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).



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**CM200HG-130H**  
**Single IGBTMOD™ HVIGBT Module**  
 200 Amperes/6500 Volts

**Static Electrical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current*	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V, T_j = 25^\circ\text{C}$	-	-	3.0	mA
		$V_{CE} = V_{CES}, V_{GE} = 0V, T_j = 125^\circ\text{C}$	-	10	30.0	mA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 20\text{mA}, V_{CE} = 10V$	5.0	6.0	7.0	Volts
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	0.5	$\mu\text{A}$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 200\text{A}, V_{GE} = 15V, T_j = 25^\circ\text{C}$	-	5.1	-	Volts
		$I_C = 200\text{A}, V_{GE} = 15V, T_j = 125^\circ\text{C}$	-	5.0	-	Volts
Input Capacitance	$C_{ies}$	$V_{CE} = 10V, V_{GE} = 0V,$	-	41.0	-	nF
Output Capacitance	$C_{oes}$	$f = 100\text{kHz},$	-	2.5	-	nF
Reverse Transfer Capacitance	$C_{res}$	$T_j = 25^\circ\text{C}$	-	0.7	-	nF
Total Gate Charge	$Q_G$	$V_{CC} = 3600V, I_C = 200\text{A}, V_{GE} = 15V$	-	3.3	-	$\mu\text{C}$
Emitter-Collector Voltage**	$V_{EC}$	$I_E = 200\text{A}, V_{GE} = 0V, T_j = 25^\circ\text{C}$	-	4.0	-	Volts
		$I_E = 200\text{A}, V_{GE} = 0V, T_j = 125^\circ\text{C}$	-	3.6	-	Volts
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 3600V, I_C = 200\text{A},$	-	1.2	-	$\mu\text{s}$
Turn-On Rise Time	$t_r$	$V_{GE1} = -V_{GE2} = 15V, R_{G(on)} = 30\Omega,$	-	0.35	-	$\mu\text{s}$
Turn-On Switching Energy	$E_{on}$	$T_j = 125^\circ\text{C}, t_{off} = 60\mu\text{s}, \text{Inductive Load}$	-	1.5	-	J/P
Turn-Off Delay Time	$t_{d(off)}$	$V_{CC} = 3600V, I_C = 200\text{A},$	-	6.6	-	$\mu\text{s}$
Turn-Off Fall Time 1	$t_{f1}$	$V_{GE1} = -V_{GE2} = 15V,$	-	0.5	-	$\mu\text{s}$
Turn-Off Fall Time 2	$t_{f2}$	$R_{G(off)} = 72\Omega,$	-	3.3	-	$\mu\text{s}$
Turn-Off Switching Energy	$E_{off}$	$T_j = 125^\circ\text{C}, t_{off} = 60\mu\text{s}, \text{Inductive Load}$	-	1.2	-	J/P
Reverse Recovery Time 1**	$t_{rr1}$	$V_{CC} = 3600V, I_E = 200\text{A},$	-	1.0	-	$\mu\text{s}$
Reverse Recovery Time 2**	$t_{rr2}$	$di_e/dt = -670\text{A}/\mu\text{s},$	-	2.4	-	$\mu\text{s}$
Reverse Recovery Charge**	$Q_{rr}$	$T_j = 125^\circ\text{C},$	-	370	-	$\mu\text{C}$
Reverse Recovery Energy**	$E_{rec}$	$t_{off} = 60\mu\text{s}, \text{Inductive Load}$	-	0.7	-	J/P

\* Pulse width and repetition rate should be such that device junction temperature rise is negligible.

\*\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

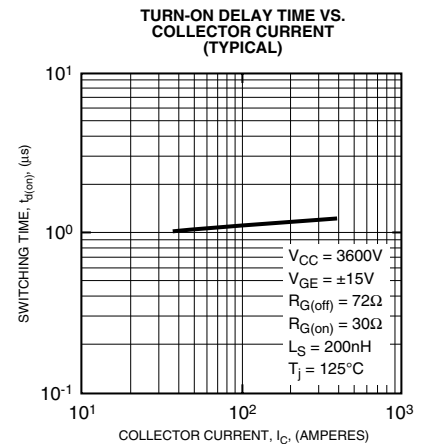
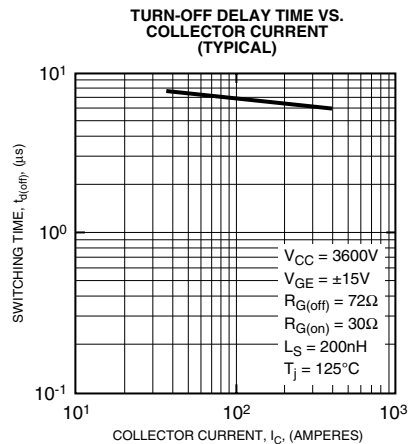
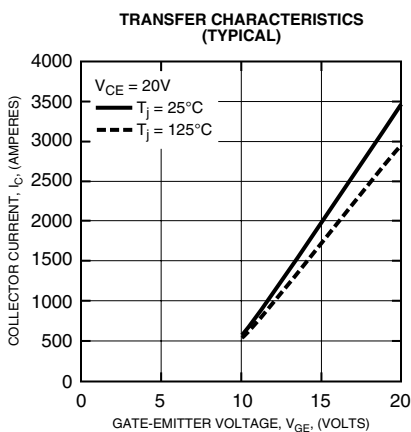
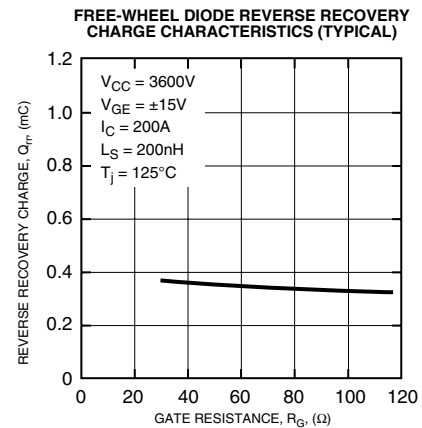
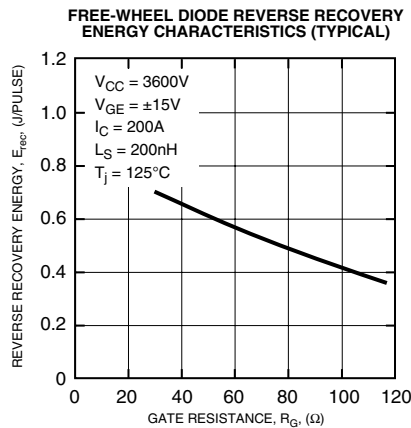
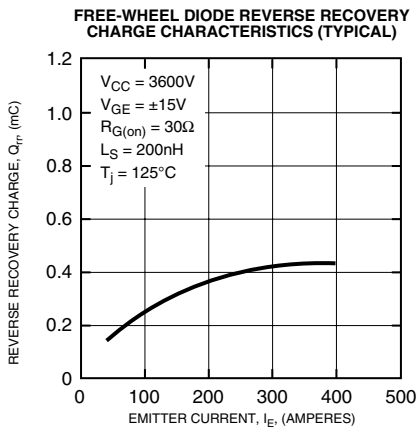
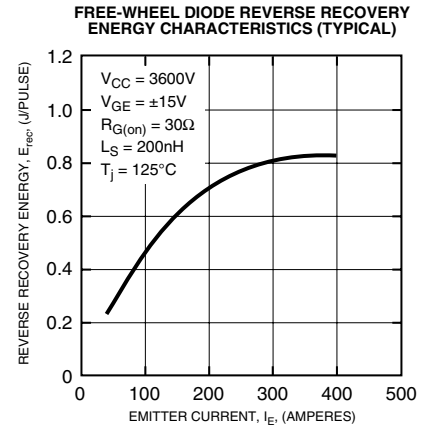
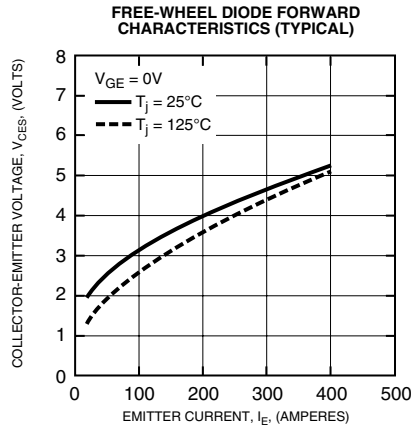
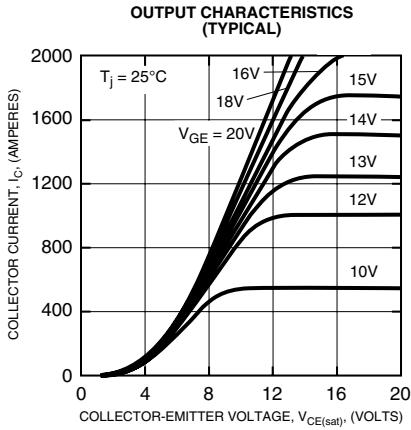
**Thermal Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}$ Q	Per IGBT	-	-	42.0	K/kW
Thermal Resistance, Junction to Case	$R_{th(j-c)}$ D	Per FWDi	-	-	66.0	K/kW
Contact Thermal Resistance, Case to Fin	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	-	18.0	-	K/kW

**Mechanical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Comparative Tracking Index	CTI	-	600	-	-	-
Clearance	-	-	26.0	-	-	mm
Creepage Distance	-	-	56.0	-	-	mm
Internal Inductance	$L_{C-E(int)}$	-	-	54.0	-	$\mu\text{H}$
Internal Lead Resistance	$R_{C-E(int)}$	-	-	-	-	m $\Omega$

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